



SOLDER CONNECTION

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QUALITEK® Technical Bulletin

PF708 Water Soluble Paste Flux

DESCRIPTION

PF708 is a mixture of organic acid, thixotropic thickeners and surfactant, which aid in water removal of post soldering residues.

FEATURES & BENEFITS

- Rapid wetting on all types of substrates
- Easily dispensed from syringes
- Residues easily removed

TECHNICAL DATA

	Specification	Test Method
Flux Type	Water Soluble	IPC-J-STD-004B
Flux Classification	ORM0	
Colour & Appearance	Amber Solid	IPC-TM-650 2.3.32
Copper Mirror	Pass	IPC-TM-650 2.6.15
Silver Chromate	Pass	IPC-TM-650 2.6.3.3
SIR	>1.0 x 10 ⁹ ohms	
pH Value	7.0 – 8.0	
Storage Temp	40 – 50 °F	
Shelf Life	6 Months from DOM	

APPLICATION METHODS

Paste Fluxes are recommended for touch up and repair of surface mount assemblies. Paste Fluxes may be applied by brush or dispensed from a syringe in the appropriate areas, then heated using conventional methods.

RESIDUE REMOVAL

PF708 requires only hot deionized water (120 °F) for residue removal.

DISPOSAL

Paste Flux should be stored in a sealed container and disposed of in accordance with federal, state and local authority requirements.

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